# **Dual Precision Monostable Multivibrator (Retriggerable, Resettable)**

The MC74HC4538A is identical in pinout to the MC14538B. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This dual monostable multivibrator may be triggered by either the positive or the negative edge of an input pulse, and produces a precision output pulse over a wide range of pulse widths. Because the device has conditioned trigger inputs, there are no trigger—input rise and fall time restrictions. The output pulse width is determined by the external timing components,  $R_x$  and  $C_x$ . The device has a reset function which forces the Q output low and the  $\overline{Q}$  output high, regardless of the state of the output pulse circuitry.

# **Features**

- Unlimited Rise and Fall Times Allowed on the Trigger Inputs
- Output Pulse is Independent of the Trigger Pulse Width
- ± 10% Guaranteed Pulse Width Variation from Part to Part (Using the Same Test Jig)
- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 3.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard
   No. 7A
- Chip Complexity: 145 FETs or 36 Equivalent Gates
- Pb-Free Packages are Available\*



# ON Semiconductor®

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# MARKING DIAGRAMS



PDIP-16 N SUFFIX CASE 648





SOIC-16 D SUFFIX CASE 751B





TSSOP-16 DT SUFFIX CASE 948F





SOEIAJ-16 F SUFFIX CASE 966



A = Assembly Location

L, WL = Wafer Lot
Y, YY = Year
W, WW = Work Week
G = Pb-Free Package
= Pb-Free Package

(Note: Microdot may be in either location)

# ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

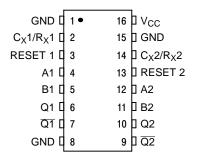


Figure 1. Pin Assignment

# **FUNCTION TABLE**

	Inputs	Outputs				
Reset	Α	В	Q	Q		
H H	۲ /	Η	片片	几		
H H	X H	L X	Not Triggered Not Triggered			
H H	L,H, ∕ L	H L,H, ∠		ggered ggered		
	X X	X	L Not Tri	H ggered		

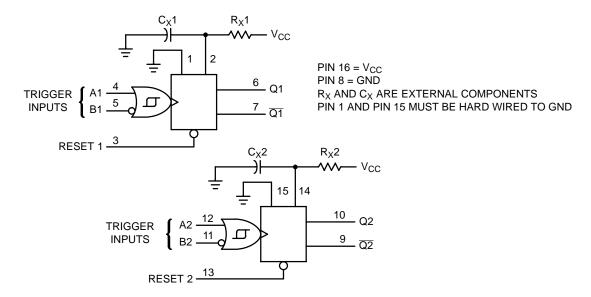


Figure 2. Logic Diagram

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74HC4538AN	PDIP-16	500 Units / Box
MC74HC4538ANG	PDIP-16 (Pb-Free)	500 Units / Box
MC74HC4538AD	SOIC-16	48 Units / Rail
MC74HC4538ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC4538ADR2	SOIC-16	2500 Units / Reel
MC74HC4538ADR2G	SOIC-16 (Pb-Free)	2500 Units / Reel
MC74HC4538ADTR2	TSSOP-16*	2500 Units / Reel
MC74HC4538ADTR2G	TSSOP-16*	2500 Units / Reel
MC74HC4538AF	SOEIAJ-16	50 Units / Rail
MC74HC4538AFG	SOEIAJ-16 (Pb-Free)	50 Units / Rail
MC74HC4538AFEL	SOEIAJ-16	2000 Units / Reel
MC74HC4538AFELG	SOEIAJ-16 (Pb-Free)	2000 Units / Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>This package is inherently Pb-Free.

#### **MAXIMUM RATINGS**

Symbol	F	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5  to  +7.0	V
VI	DC Input Voltage		$-0.5 \le V_{I} \le V_{CC} + 0.5$	V
Vo	DC Output Voltage	(Note 1)	$-0.5 \le V_{O} \le V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current	±20 ±30	mA	
I <sub>OK</sub>	DC Output Diode Current		±25	mA
I <sub>O</sub>	DC Output Sink Current		±25	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		±100	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead temperature, 1 mm from Case f	or 10 Seconds	260	°C
TJ	Junction temperature under Bias		+ 150	°C
$\theta_{\sf JA}$	Thermal resistance	PDIP SOIC TSSOP	78 112 148	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 85°C	PDIP SOIC TSSOP	750 500 450	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 30% – 35%	UL-94-VO (0.125 in)	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	>2000 >100 >500	V
I <sub>Latchup</sub>	Latchup Performance	Above V <sub>CC</sub> and Below GND at 85°C (Note 5)	±300	mA

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- I<sub>O</sub> absolute maximum rating must be observed.
   Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.
- 6. For high frequency or heavy load considerations, see the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

# RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	3.0*	6.0	V	
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0	V <sub>CC</sub>	V	
T <sub>A</sub>	Operating Temperature, All Package Types		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time $V_{CC} = (Figure 7)$ $V_{CC} = V_{CC} =$	= 2.0 V = 4.5 V = 6.0 V	0 0 0 -	1000 500 400 No Limit	ns
R <sub>x</sub>	External Timing Resistor V <sub>CC</sub> < V <sub>CC</sub> ≥	< 4.5 V 4.5 V	1.0 2.0	† †	kΩ
C <sub>x</sub>	External Timing Capacitor		0	†	μF

<sup>\*</sup>The HC4538A will function at 2.0 V but for optimum pulse–width stability,  $V_{CC}$  should be above 3.0 V. †The maximum allowable values of  $R_x$  and  $C_x$  are a function of the leakage of capacitor  $C_x$ , the leakage of the HC4538A, and leakage due to board layout and surface resistance. For most applications,  $C_X/R_X$  should be limited to a maximum value of 10  $\mu$ F/1.0  $M\Omega$ . Values of  $C_X > 1.0$   $\mu$ F may cause a problem during power down (see Power Down Considerations). Susceptibility to externally induced noise signals may occur for R<sub>x</sub> > 1.0 MΩ.

<sup>7.</sup> Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

<sup>8.</sup> Information on typical parametric values can be found in the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

# **DC CHARACTERISTICS**

					G	uarante	ed Limit	s		
			V <sub>CC</sub>	–55 to	25°C	≤ 8	35°C	≤ 1	25°C	
Symbol	Parameter	Test Conditions	VCC	Min	Max	Min	Max	Min	Max	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \le 20  \mu\text{A}$	2.0 4.5 6.0	1.5 3.15 4.2		1.5 3.15 4.2		1.5 3.15 4.2		V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{out}  \le 20  \mu\text{A}$	2.0 4.5 6.0		0.5 1.35 1.8		0.5 1.35 1.8		0.5 1.35 1.8	V
V <sub>OH</sub>	Minimum High-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \ \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9		1.9 4.4 5.9		1.9 4.4 5.9		V
		$\begin{split} &V_{in} = V_{IH} \text{ or } V_{IL} \\ & I_{out}  \leq -4.0 \text{ mA} \\ & I_{out}  \leq -5.2 \text{ mA} \end{split}$	4.5 6.0	3.98 5.48		3.84 5.34		3.7 5.2		
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20  \mu\text{A}$	2.0 4.5 6.0		0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 4.0 \text{ mA}$ $ I_{out}  \le 5.2 \text{ mA}$	4.5 6.0		0.26 0.26		0.33 0.33		0.4 0.4	
l <sub>in</sub>	Maximum Input Leakage Current (A, B, Reset)	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0		± 0.1		± 1.0		± 1.0	μΑ
I <sub>in</sub>	Maximum Input Leakage Current (R <sub>x</sub> , C <sub>x</sub> )	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0		± 50		± 500		± 500	nA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per package) Standby State	$V_{in} = V_{CC}$ or GND Q1 and Q2 = Low $I_{out} = 0 \mu A$	6.0		130		220		350	μΑ
I <sub>CC</sub>	Maximum Supply Current (per package) Active State	$V_{in} = V_{CC}$ or GND Q1 and Q2 = High $I_{out} = 0 \mu A$		25	i°C		°C to i°C		°C to 5°C	
		Pins 2 and 14 = 0.5 $V_{CC}$	6.0		400		600		800	μΑ

# AC CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6.0 \text{ ns}$ )

				G	uarante	ed Limit	ts		
		v <sub>cc</sub>	–55 to 25°C		≤ 85°C		≤ 125°C		
Symbol	Parameter	VCC	Min	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub>	Maximum Propagation Delay Input A or B to Q (Figures 6 and 8)	2.0 4.5 6.0		175 35 30		220 44 37		265 53 45	ns
t <sub>PHL</sub>	Maximum Propagation Delay Input A or B to NQ (Figures 6 and 8)	2.0 4.5 6.0		195 39 33		245 49 42		295 59 50	ns
t <sub>PHL</sub>	Maximum Propagation Delay Reset to Q (Figures 7 and 8)	2.0 4.5 6.0		175 35 30		220 44 37		265 53 45	ns
t <sub>PLH</sub>	Maximum Propagation Delay Reset to NQ (Figures 7 and 8)	2.0 4.5 6.0		175 35 30		220 44 37		265 53 45	ns
t <sub>TLH,</sub> t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 7 and 8)	2.0 4.5 6.0		75 15 13		95 19 16		110 22 19	ns
C <sub>in</sub>		-		10 25		10 25		10 25	pF

<sup>9.</sup> For propagation delays with loads other than 50 pF, and information on typical parametric values, see the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (per Multivibrator)*	150	pF

<sup>\*</sup>Used to determine the no–load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ . For load considerations, see the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

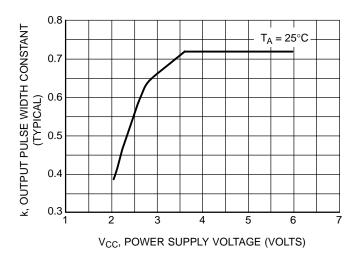
# **TIMING CHARACTERISTICS** (Input $t_r = t_f = 6.0 \text{ ns}$ )

				G	uarante	ed Limit	s		
		V	–55 to 25°C		≤ 85°C		≤ 125°C		1
Symbol	Parameter	V <sub>CC</sub>	Min	Max	Min	Max	Min	Max	Unit
t <sub>rec</sub>	Minimum Recovery Time, Inactive to A or B (Figure 7)	2.0 4.5 6.0	0 0 0		0 0 0		0 0 0		ns
t <sub>w</sub>	Minimum Pulse Width, Input A or B (Figure 6)	2.0 4.5 6.0	60 12 10		75 15 13		90 18 15		ns
t <sub>w</sub>	Minimum Pulse Width, Reset (Figure 7)	2.0 4.5 6.0	60 12 10		75 15 13		90 18 15		ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times, Reset (Figure 7)	2.0 4.5 6.0		1000 500 400		1000 500 400		1000 500 400	ns
	A or B (Figure 7)	2.0 4.5 6.0		•	No	Limit	•	•	

# **OUTPUT PULSE WIDTH CHARACTERISTICS** (C<sub>L</sub> = 50 pF)t

		Conditions	Conditions		G	Guaranteed Limits				
			V <sub>CC</sub>		°C ≤ 85°C		25°C			
Symbol	Parameter	Timing Components	v	Min	Max	Min	Max	Min	Max	Unit
τ	Output Pulse Width* (Figures 6 and 8)	$R_x = 10 \text{ k}\Omega, C_x = 0.1 \mu\text{F}$	5.0	0.63	0.77	0.6	0.8	0.59	0.81	ms
_	Pulse Width Match Between Circuits in the same Package	-	-			± 5.0			%	
_	Pulse Width Match Variation (Part to Part)	-	-	± 10			%			

<sup>\*</sup>For output pulse widths greater than 100  $\mu$ s, typically  $\tau = kR_xC_x$ , where the value of k may be found in Figure 3.



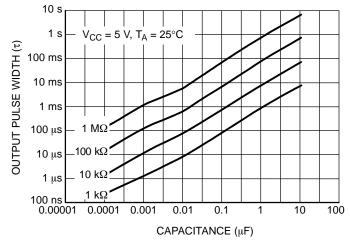


Figure 3. Typical Output Pulse Width Constant, k, versus Supply Voltage (For output pulse widths > 100  $\mu$ s:  $\tau = kR_xC_x$ )

Figure 4. Output Pulse Width versus Timing Capacitance

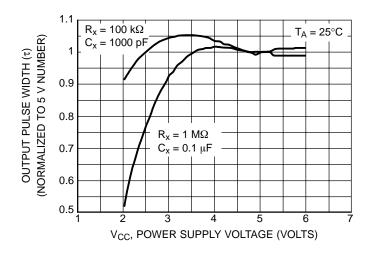


Figure 5. Normalized Output Pulse Width versus Power Supply Voltage

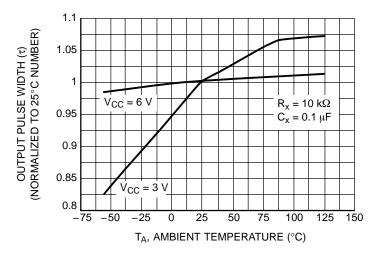


Figure 6. Normalized Output Pulse Width versus Power Supply Voltage

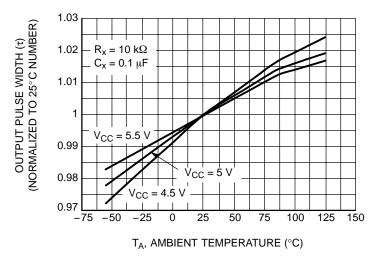


Figure 7. Normalized Output Pulse Width versus Power Supply Voltage

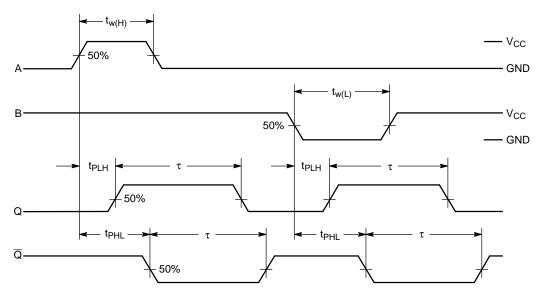


Figure 8. Switching Waveform

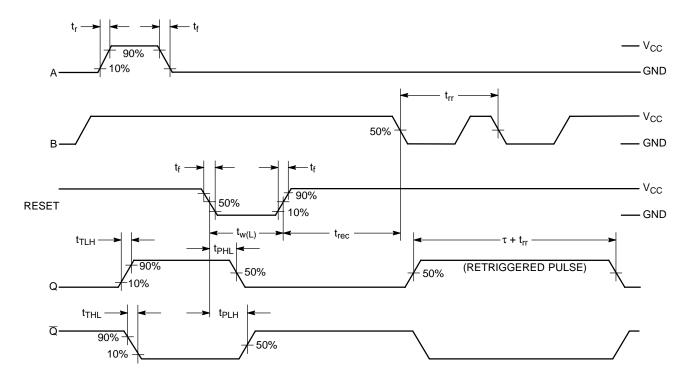
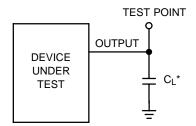


Figure 9. Switching Waveform



\*Includes all probe and jig capacitance

Figure 10. Test Circuit

#### PIN DESCRIPTIONS

#### **INPUTS**

# A1, A2 (Pins 4, 12)

Positive–edge trigger inputs. A rising–edge signal on either of these pins triggers the corresponding multivibrator when there is a high level on the B1 or B2 input.

# B1, B2 (Pins 5, 11)

Negative—edge trigger inputs. A falling—edge signal on either of these pins triggers the corresponding multivibrator when there is a low level on the A1 or A2 input.

# Reset 1, Reset 2 (Pins 3, 13)

Reset inputs (active low). When a low level is applied to one of these pins, the Q output of the corresponding multivibrator is reset to a low level and the  $\overline{Q}$  output is set to a high level.

# $C_X 1/R_X 1$ and $C_X 2/R_X 2$ (Pins 2 and 14)

External timing components. These pins are tied to the common points of the external timing resistors and

capacitors (see the Block Diagram). Polystyrene capacitors are recommended for optimum pulse width control. Electrolytic capacitors are not recommended due to high leakages associated with these type capacitors.

# **GND (Pins 1 and 15)**

External ground. The external timing capacitors discharge to ground through these pins.

# **OUTPUTS**

# Q1, Q2 (Pins 6, 10)

Noninverted monostable outputs. These pins (normally low) pulse high when the multivibrator is triggered at either the A or the B input. The width of the pulse is determined by the external timing components,  $R_X$  and  $C_X$ .

# Q1, Q2 (Pins 7, 9)

Inverted monostable outputs. These pins (normally high) pulse low when the multivibrator is triggered at either the A or the B input. These outputs are the inverse of Q1 and Q2.

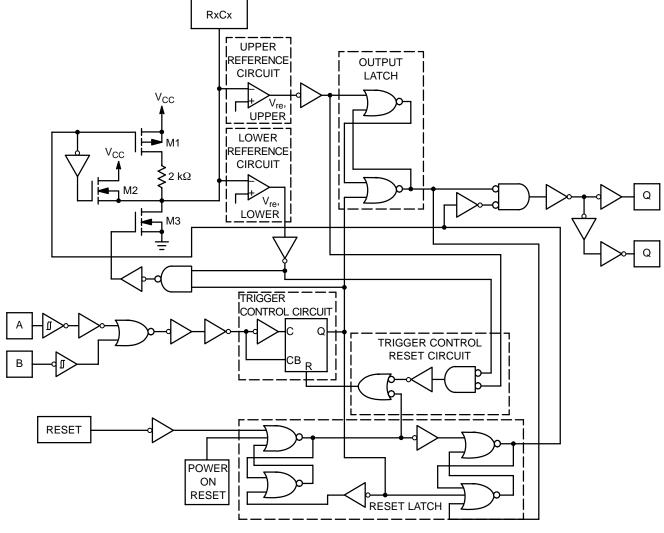


Figure 11. Logic Detail (1/2 the Device)

#### CIRCUIT OPERATION

Figure 12 shows the HC4538A configured in the retriggerable mode. Briefly, the device operates as follows (refer to Figure 10): In the quiescent state, the external timing capacitor,  $C_x$ , is charged to  $V_{CC}$ . When a trigger occurs, the Q output goes high and  $C_x$  discharges quickly to the lower reference voltage ( $V_{ref}$  Lower  $\approx 1/3$   $V_{CC}$ ).  $C_x$  then charges, through  $R_x$ , back up to the upper reference voltage ( $V_{ref}$  Upper  $\approx 2/3$   $V_{CC}$ ), at which point the one–shot has timed out and the Q output goes low.

The following, more detailed description of the circuit operation refers to both the logic detail (Figure 9) and the timing diagram (Figure 10).

# **QUIESCENT STATE**

In the quiescent state, before an input trigger appears, the output latch is high and the reset latch is high (#1 in Figure 10). Thus the Q output (pin 6 or 10) of the monostable multivibrator is low (#2, Figure 10).

The output of the trigger–control circuit is low (#3), and transistors M1, M2, and M3 are turned off. The external timing capacitor,  $C_x$ , is charged to  $V_{CC}$  (#4), and both the upper and lower reference circuit has a low output (#5).

In addition, the output of the trigger-control reset circuit is low.

#### TRIGGER OPERATION

The HC4538A is triggered by either a rising–edge signal at input A (#7) or a falling–edge signal at input B (#8), with the unused trigger input and the Reset input held at the voltage levels shown in the Function Table. Either trigger signal will cause the output of the trigger–control circuit to go high (#9).

The trigger–control circuit going high simultaneously initiates two events. First, the output latch goes low, thus taking the Q output of the HC4538A to a high state (#10). Second, transistor M3 is turned on, which allows the external timing capacitor,  $C_x$ , to rapidly discharge toward ground (#11). (Note that the voltage across  $C_x$  appears at the input of both the upper and lower reference circuit comparator).

When  $C_x$  discharges to the reference voltage of the lower reference circuit (#12), the outputs of both reference circuits will be high (#13). The trigger–control reset circuit goes high, resetting the trigger–control circuit flip–flop to a low state (#14). This turns transistor M3 off again, allowing  $C_x$  to begin to charge back up toward  $V_{CC}$ , with a time constant  $t = R_x C_x$  (#15). Once the voltage across  $C_x$  charges to above the lower reference voltage, the lower reference circuit will go low allowing the monostable multivibrator to be retriggered.

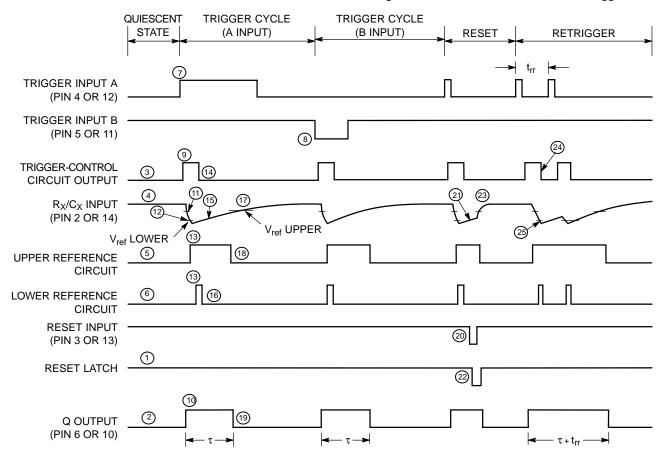


Figure 12. Timing Diagram

When  $C_x$  charges up to the reference voltage of the upper reference circuit (#17), the output of the upper reference circuit goes low (#18). This causes the output latch to toggle, taking the Q output of the HC4538A to a low state (#19), and completing the time—out cycle.

# POWER-DOWN CONSIDERATIONS

Large values of  $C_x$  may cause problems when powering down the HC4538A because of the amount of energy stored in the capacitor. When a system containing this device is powered down, the capacitor may discharge from  $V_{CC}$  through the input protection diodes at pin 2 or pin 14. Current through the protection diodes must be limited to 30 mA; therefore, the turn–off time of the  $V_{CC}$  power supply must not be faster than  $t = V_{CC} \cdot C_x/(30 \text{ mA})$ . For example, if  $V_{CC} = 5.0 \text{ V}$  and  $C_x = 15 \,\mu\text{F}$ , the  $V_{CC}$  supply must turn off no faster than  $t = (5.0 \text{ V}) \cdot (15 \,\mu\text{F})/30 \text{ mA} = 2.5 \text{ ms}$ . This is usually not a problem because power supplies are heavily filtered and cannot discharge at this rate.

When a more rapid decrease of  $V_{CC}$  to zero volts occurs, the HC4538A may sustain damage. To avoid this possibility, use an external damping diode,  $D_x$ , connected as shown in Figure 11. Best results can be achieved if diode  $D_x$  is chosen to be a germanium or Schottky type diode able to withstand large current surges.

#### **RESET AND POWER ON RESET OPERATION**

A low voltage applied to the Reset pin always forces the Q output of the HC4538A to a low state.

The timing diagram illustrates the case in which reset occurs (#20) while  $C_x$  is charging up toward the reference voltage of the upper reference circuit (#21). When a reset

occurs, the output of the reset latch goes low (#22), turning on transistor M1. Thus  $C_x$  is allowed to quickly charge up to  $V_{CC}$  (#23) to await the next trigger signal.

On power up of the HC4538A the power—on reset circuit will be high causing a reset condition. This will prevent the trigger—control circuit from accepting a trigger input during this state. The HC4538A's Q outputs are low and the  $\overline{Q}$  not outputs are high.

#### RETRIGGER OPERATION

When used in the retriggerable mode (Figure 12), the HC4538A may be retriggered during timing out of the output pulse at any time after the trigger–control circuit flip–flop has been reset (#24), and the voltage across  $C_x$  is above the lower reference voltage. As long as the  $C_x$  voltage is below the lower reference voltage, the reset of the flip–flop is high, disabling any trigger pulse. This prevents M3 from turning on during this period resulting in an output pulse width that is predictable.

The amount of undershoot voltage on  $R_xC_x$  during the trigger mode is a function of loop delay, M3 conductivity, and  $V_{DD}$ . Minimum retrigger time, trr (Figure 7), is a function of 1) time to discharge  $R_xC_x$  from  $V_{DD}$  to lower reference voltage ( $T_{discharge}$ ); 2) loop delay ( $T_{delay}$ ); 3) time to charge  $R_xC_x$  from the undershoot voltage back to the lower reference voltage ( $T_{charge}$ ).

Figure 13 shows the device configured in the non-retriggerable mode.

For additional information, please see Application Note (AN1558/D) titled *Characterization of Retrigger Time in the HC4538A Dual Precision Monostable Multivibrator.* 

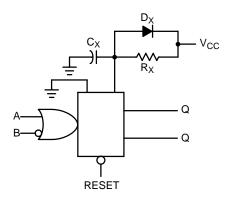
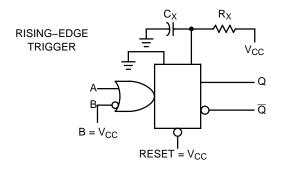
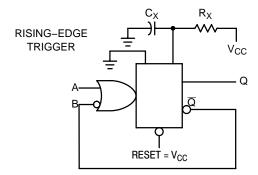
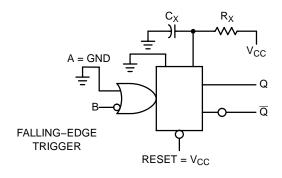


Figure 13. Discharge Protection During Power Down

# **TYPICAL APPLICATIONS**







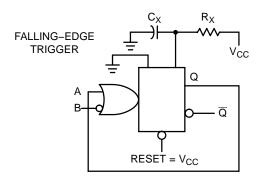


Figure 14. Retriggerable Monostable Circuitry

Figure 15. Non-retriggerable Monostable Circuitry

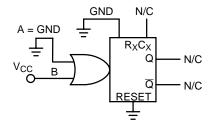
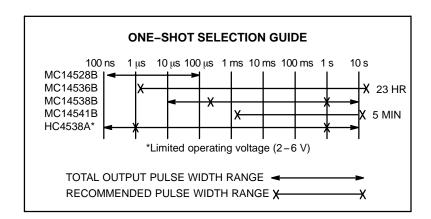
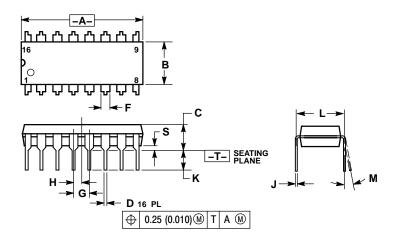


Figure 16. Connection of Unused Section



#### **PACKAGE DIMENSIONS**

# PDIP-16 **N SUFFIX** CASE 648-08 **ISSUE T**

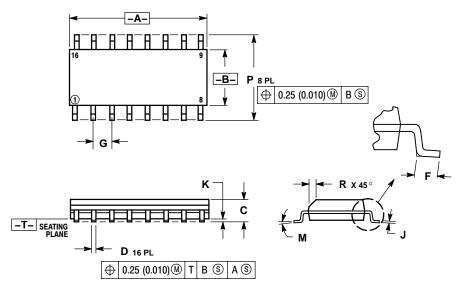


#### NOTES:

- DIMENSIONING AND TOLERANCING PER
- DIMENSIONING AND TOLERANCING F ANSI 714.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
   DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS			
DIM	MIN	MAX	MIN	MAX		
Α	0.740	0.770	18.80	19.55		
В	0.250	0.270	6.35	6.85		
С	0.145	0.175	3.69	4.44		
D	0.015	0.021	0.39	0.53		
F	0.040	0.70	1.02	1.77		
G	0.100	BSC	2.54	BSC		
Н	0.050	BSC	1.27	BSC		
J	0.008	0.015	0.21	0.38		
K	0.110	0.130	2.80	3.30		
L	0.295	0.305	7.50	7.74		
М	0°	10 °	0 °	10 °		
S	0.020	0.040	0.51	1.01		

# SOIC-16 **D SUFFIX** CASE 751B-05 **ISSUE J**



- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

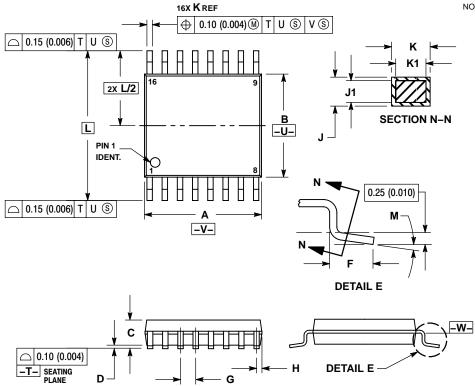
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIGN.

- MAXIMUM MOLD PHOLICISION 0.15 (0.006)
  PER SIDE.
  DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL
  IN EXCESS OF THE D DIMENSION AT
  MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050	BSC	
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0 °	7°	0 °	7°	
P	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

#### **PACKAGE DIMENSIONS**

TSSOP-16 **DT SUFFIX** CASE 948F-01 **ISSUE A** 



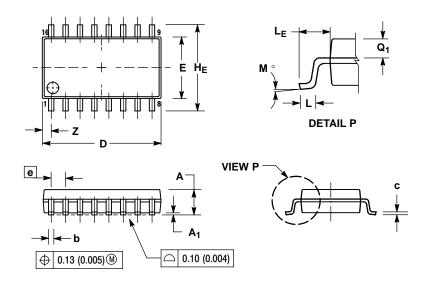
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
    2. CONTROLLING DIMENSION: MILLIMETER.
    3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
    4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
    5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K

  - (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL
  - 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
    7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
C		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026	BSC	
Н	0.18	0.28	0.007	0.011	
7	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40	BSC	0.252 BSC		
М	0°	8°	0°	8 °	

# **PACKAGE DIMENSIONS**

SOEIAJ-16 **F SUFFIX** CASE 966-01 **ISSUE O** 



#### NOTES:

- 11ES:

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (6 006) PER SIDE.
- OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

  4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

  5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27 BSC		0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.78		0.031

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